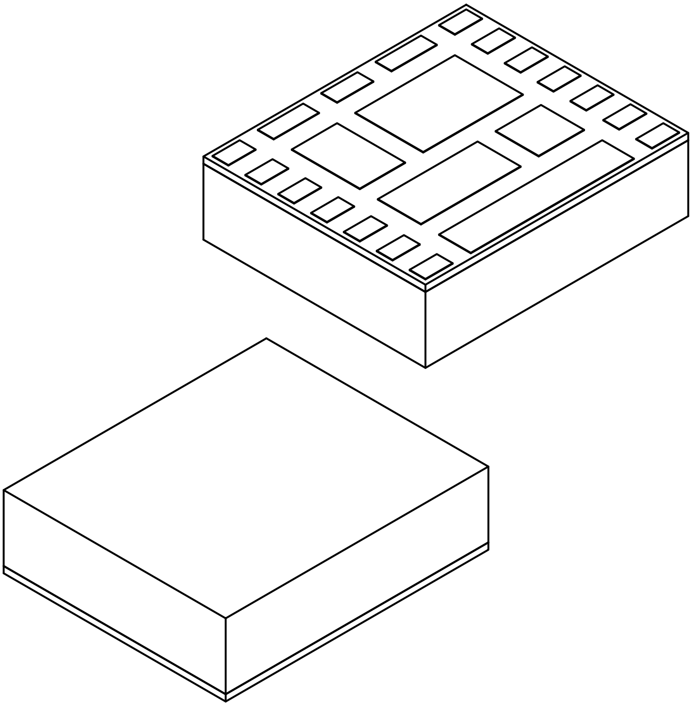
22-Lead Land Grid Array 5.8x4.9x1.71mm (8FW) [LGA] - System in Package [SIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		22	
Pitch	e		0.725 BSC	
Pitch	e1		1.300 BSC	
Overall Height	A	1.41	1.56	1.71
Overall Length	D		4.90 BSC	
Lead Pad Length Pitch	D1		4.35 REF	
Overall Width	E		5.80 BSC	
Lead Pad Width Pitch	E1		5.00 REF	
Terminal Width	b	0.30	0.35	0.40
Terminal Length	L	0.55	0.60	0.65

Notes:

1. The Pin 1 visual index feature may vary, but it must be located within the hatched area.
2. The package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerances, for information purposes only.